

NEWS RELEASE: New Book Publication

KOKI Company Limited

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'Lead-free Soldering Process Development and Reliability'

Edited by Mr. Jasbir Bath is now available at the Wiley website and SMTA website bookstore

KOKI Company Limited (Tokyo, Japan) is proud to announce that Mr. Jasbir Bath, Support Advisory Engineer of KOKI Solder America, has edited and released a book titled *Lead-free Soldering Process Development and Reliability*. The new book is available from the Wiley website and SMTA online bookstore.

The book covers major topics in lead-free soldering such as developments in process engineering, solder alloy development, intermetallic compounds, PCB surface finishes and laminates, underfills/encapsulants, conformal coatings and reliability assessments. The chapters are written by authors from OEM, EMS, soldering material and equipment supplier companies and Universities who are active in these development fields who discuss and provide insights into the most important areas to consider. Mr. Shantanu Joshi, Engineering Sales Manager of KOKI Solder America, has contributed to one of the chapters in the book, *Solder Paste and Flux Technology*.

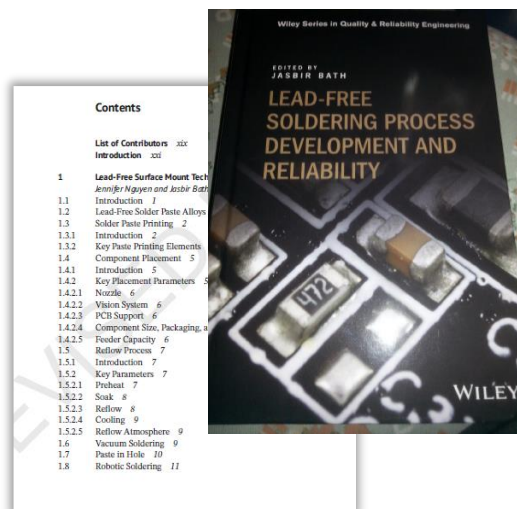
Comprehensive topics related to lead-free soldering are discussed in depth in *Lead-free Soldering Process Development and Reliability*, which will make it an ideal reference for research, development, and production. The book comprising of over 450 pages is available to purchase at the websites below.

WILEY website:

<https://www.wiley.com/en-us/Lead+free+Soldering+Process+Development+and+Reliability-p-9781119481935>

SMTA Online Store:

<https://smta.org/store/viewproduct.aspx?id=16804440>



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